DCA1000EVM

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VERSION	1.00

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VERSION HISTORY

VER #	DATE	DESCRIPTION OF CHANGES	AUTHOR	REVIEWED BY	APPROVED BY
0.10	06 DEC 2017	MODIFICATION DONE TO REV-E1 SCHEMATICS AS PER BELOW CHANGES, 1. VCC_CORE SUPPLY FEEDBACK RESISTOR VALUES CHANGED IN PAGE 4. 2. AUTO NEGOTIATION RESISTORS ADDED IN PAGE 08. 3. SPI MISO & MOSI SIGNALS SWAPPED IN PAGE 12. 4. UART TX & RX SIGNALS SWAPPED IN PAGE 12.	BALA	ALAGAPPAN	ALAGAPPAN
1.00	26 DEC 2017	REVIEWED & BASELINED	BALA	ALAGAPPAN	ALAGAPPAN

Project :

DCA1000EVM

Designed for TI by Mistral Solutions Pvt Ltd

Title VERSION HISTORY

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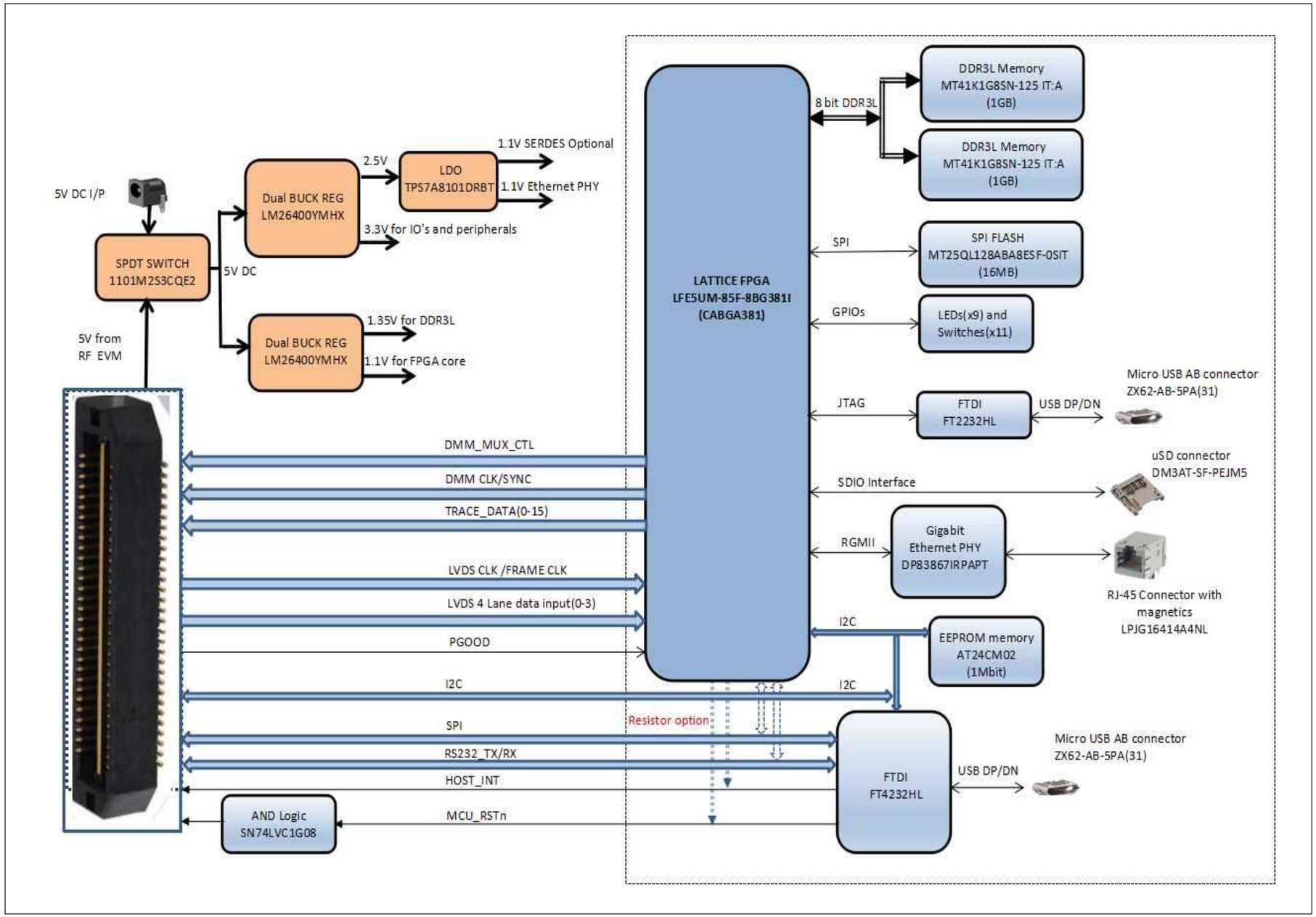
BLOCK DIAGRAM



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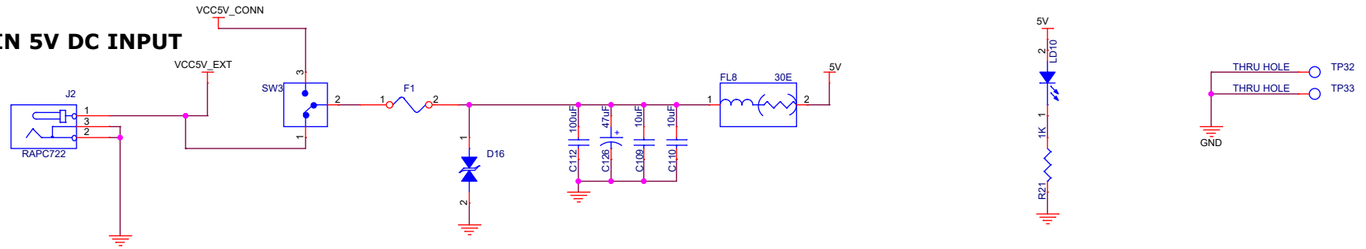
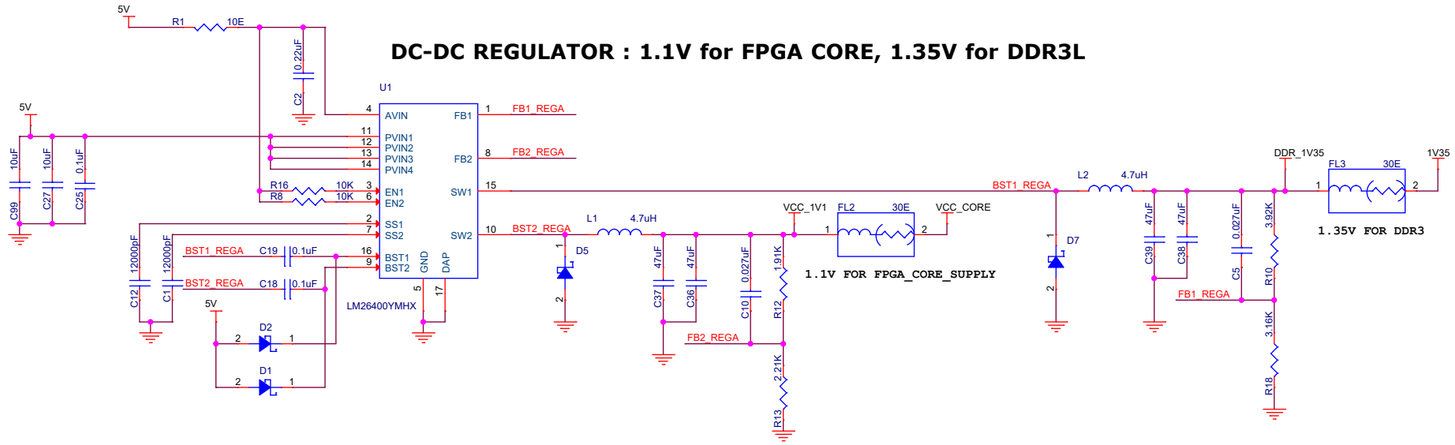
POWER_SECTION

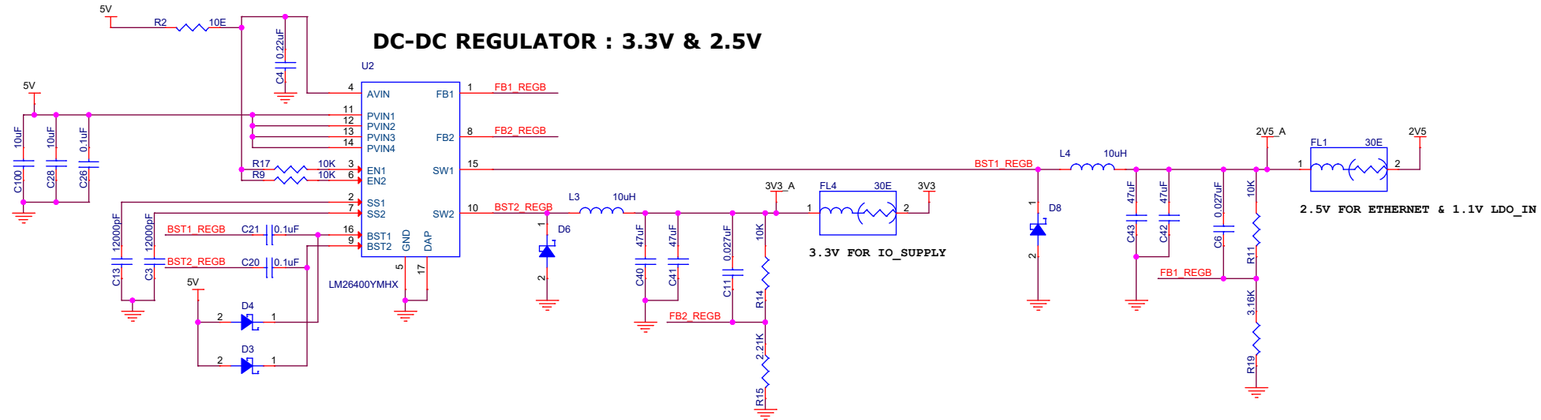
MAIN 5V DC INPUT



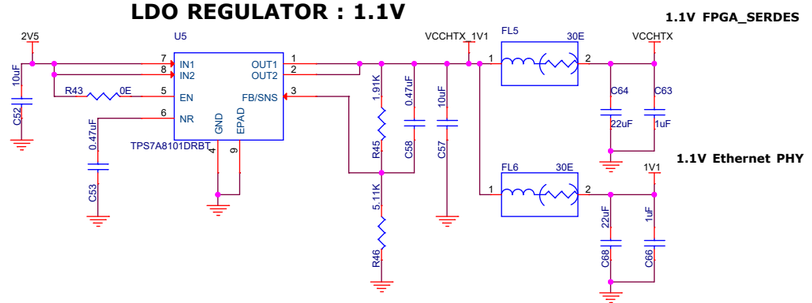
DC-DC REGULATOR : 1.1V for FPGA CORE, 1.35V for DDR3L



DC-DC REGULATOR : 3.3V & 2.5V



LDO REGULATOR : 1.1V



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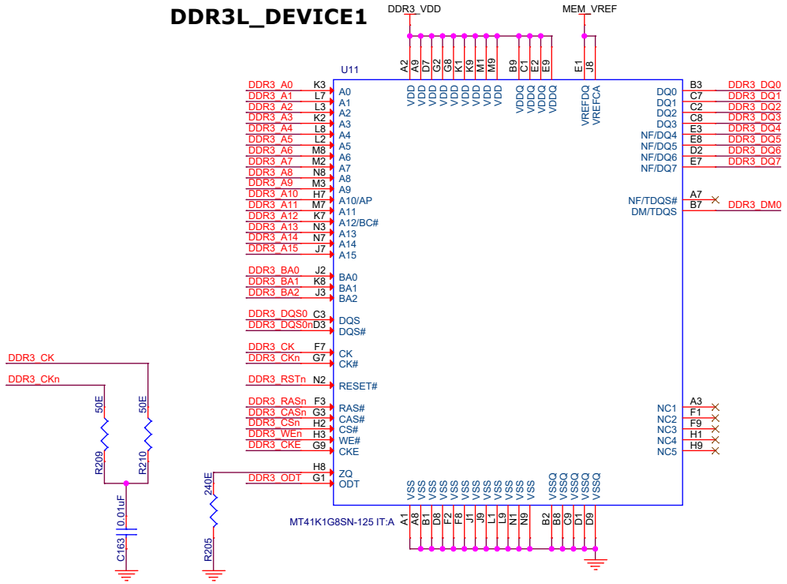
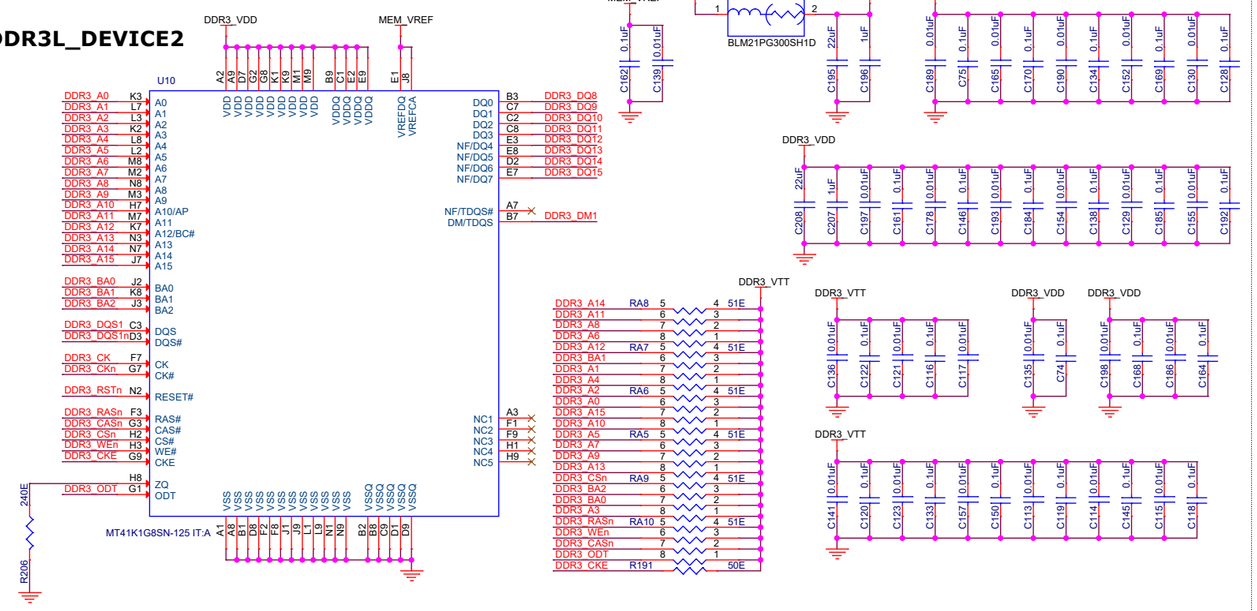
DDR3_INTERFACE

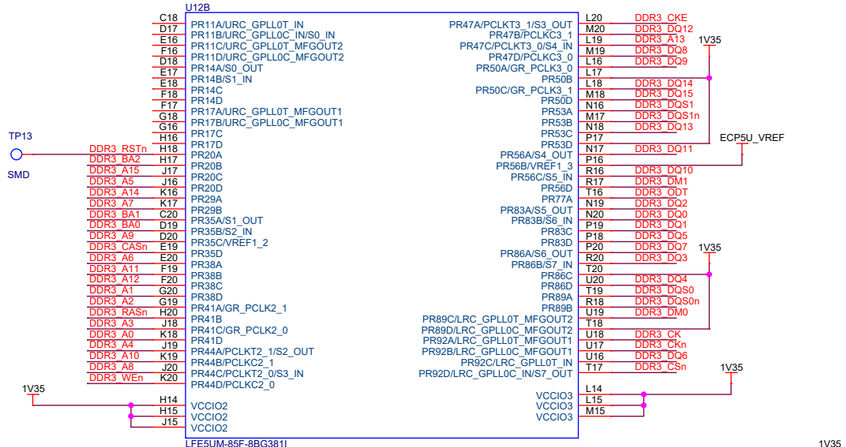
DDR3L_DEVICE1



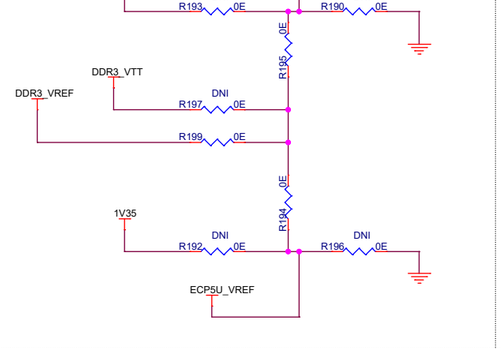
DDR3L_DEVICE2



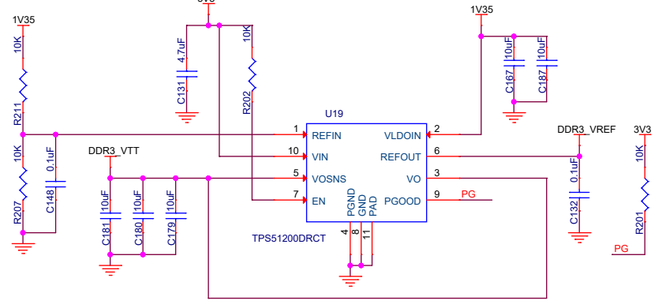
FPGA_DDR3_BANK_2&3



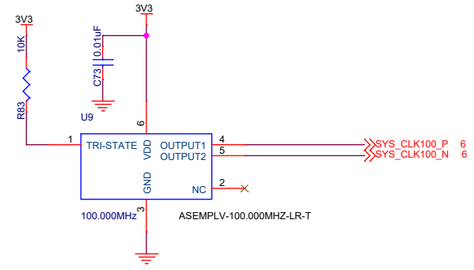
DDR3_VREF_SUPPLY_SEL



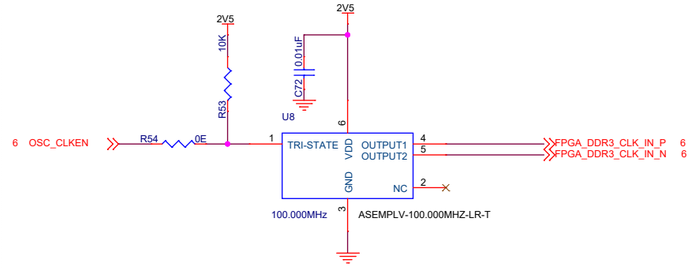
DDR3_VREF&VTT_REGULATOR



FPGA_SYS_CLK_100MHz_GENERATOR



FPGA_DDR3_100MHz_CLK_GENERATOR



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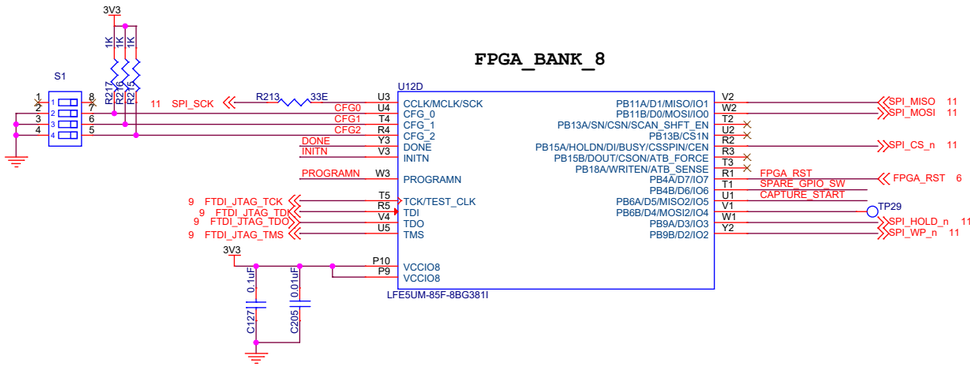
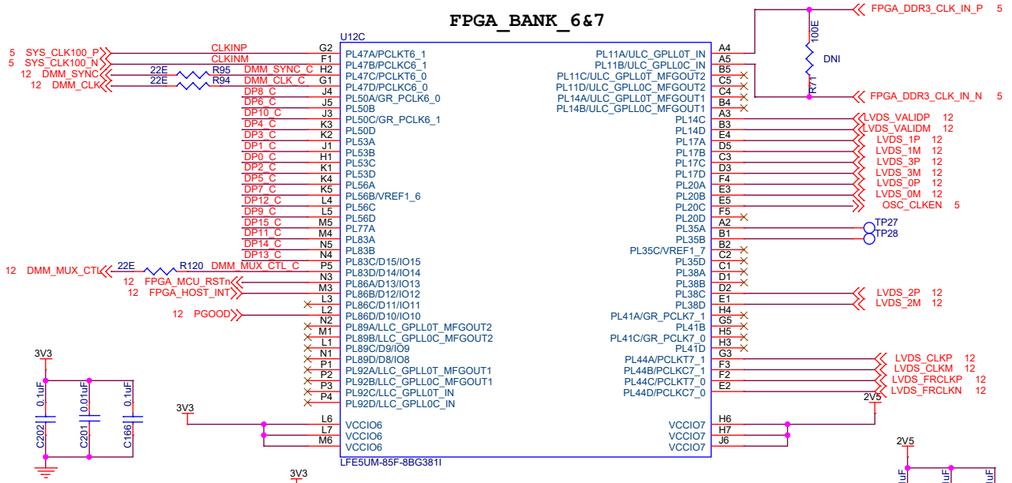
FPGA_IO_SECTION

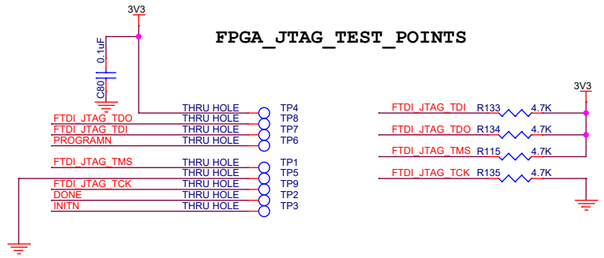
FPGA_BANK_8



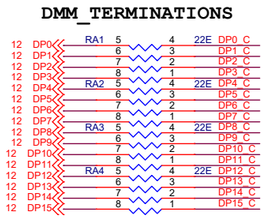
FPGA_BANK_6&7



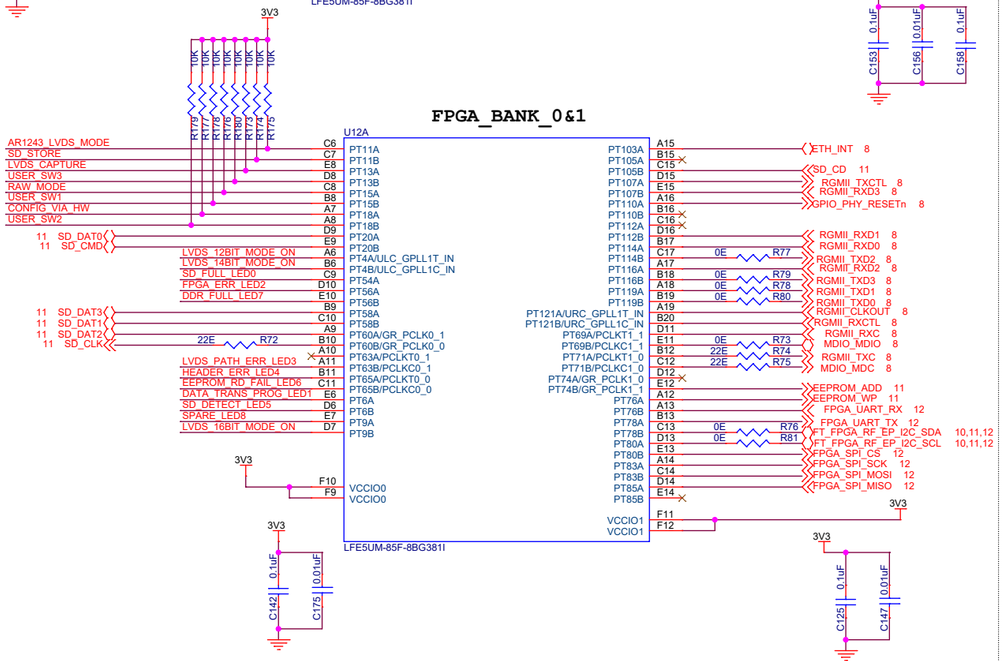
FPGA_JTAG_TEST_POINTS



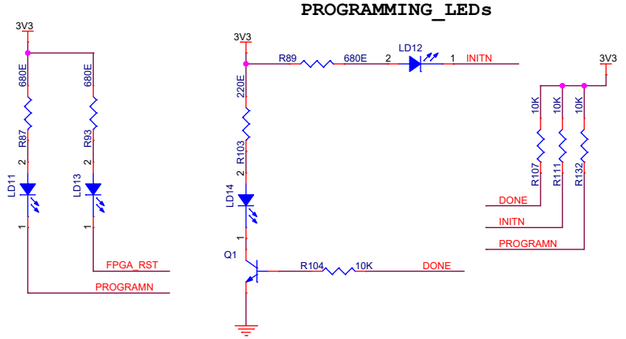
DMM_TERMINATIONS



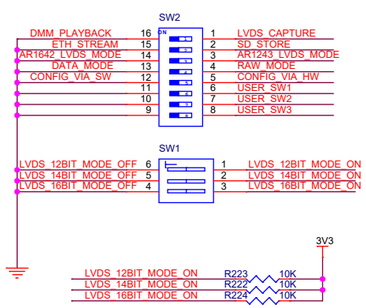
FPGA_BANK_0&1



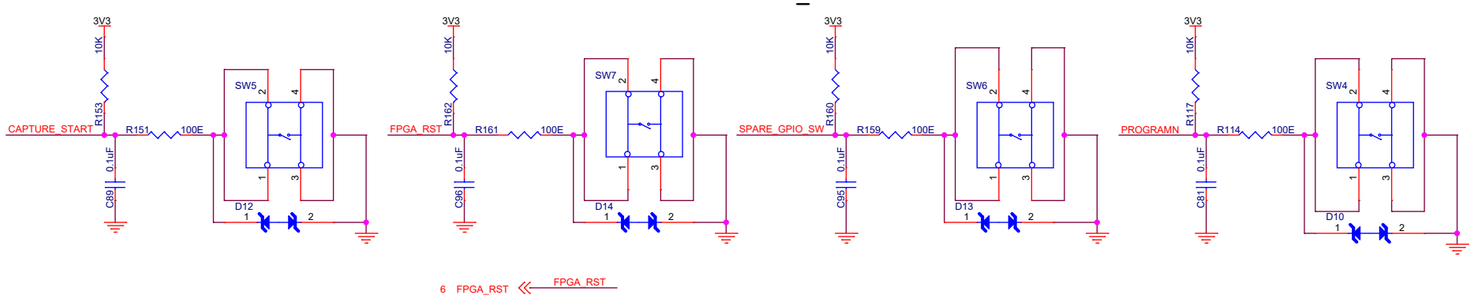
PROGRAMMING_LEDs



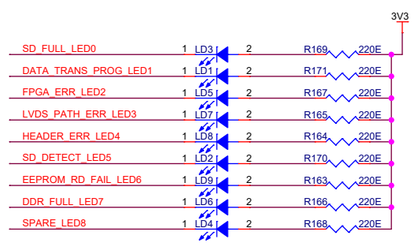
USER_CONFIG_SWITCHES



BASIC_SWITCHES



USER_LED_CIRCUIT



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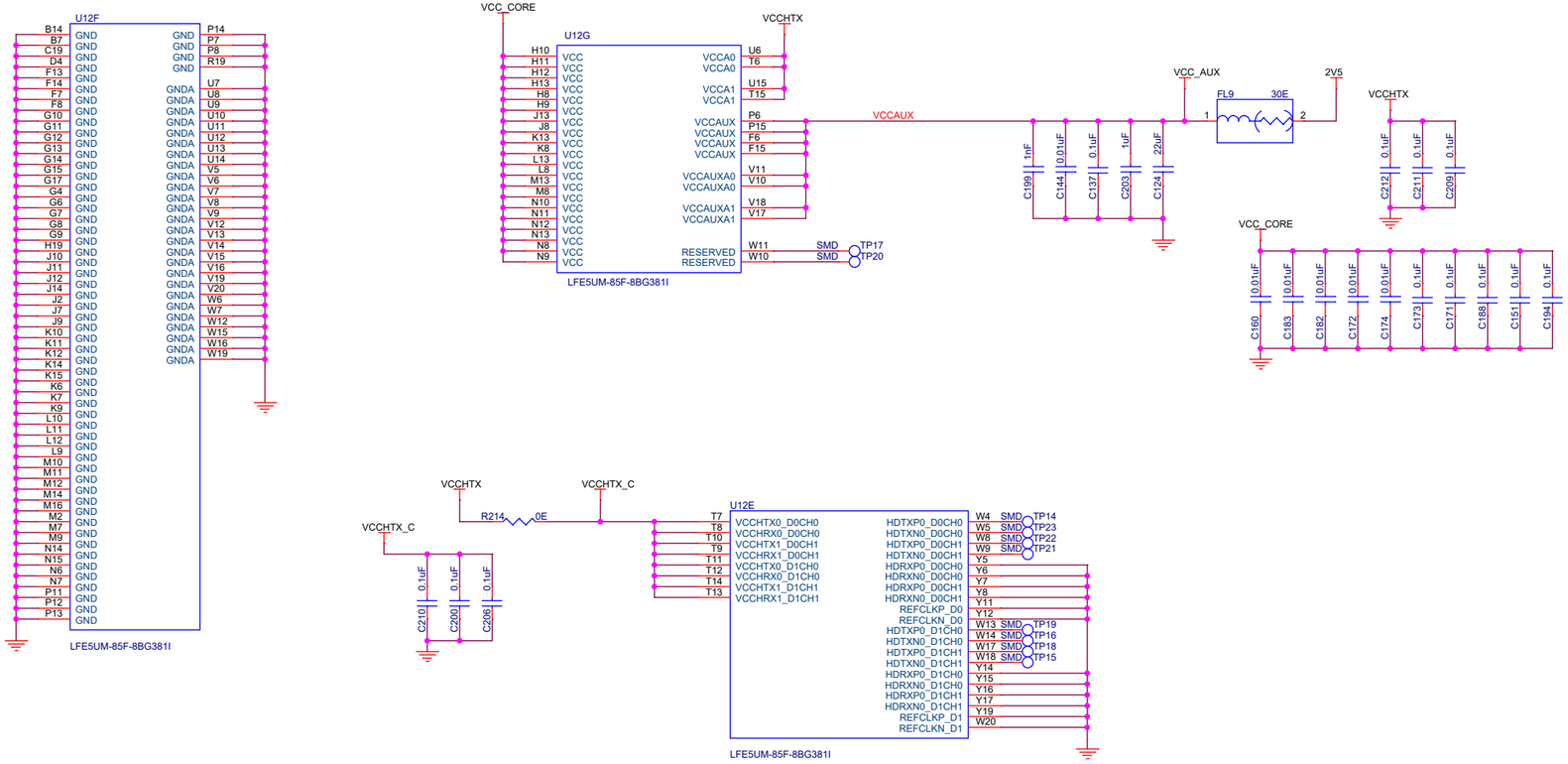
FPGA_POWER



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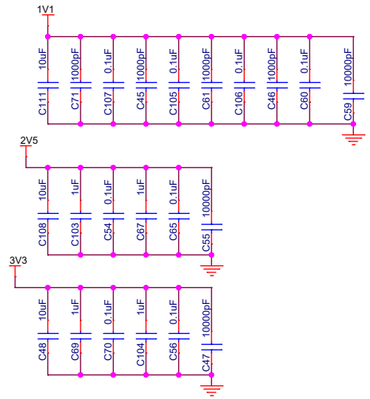
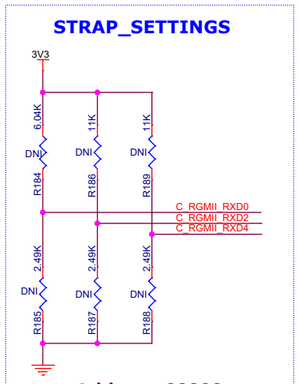
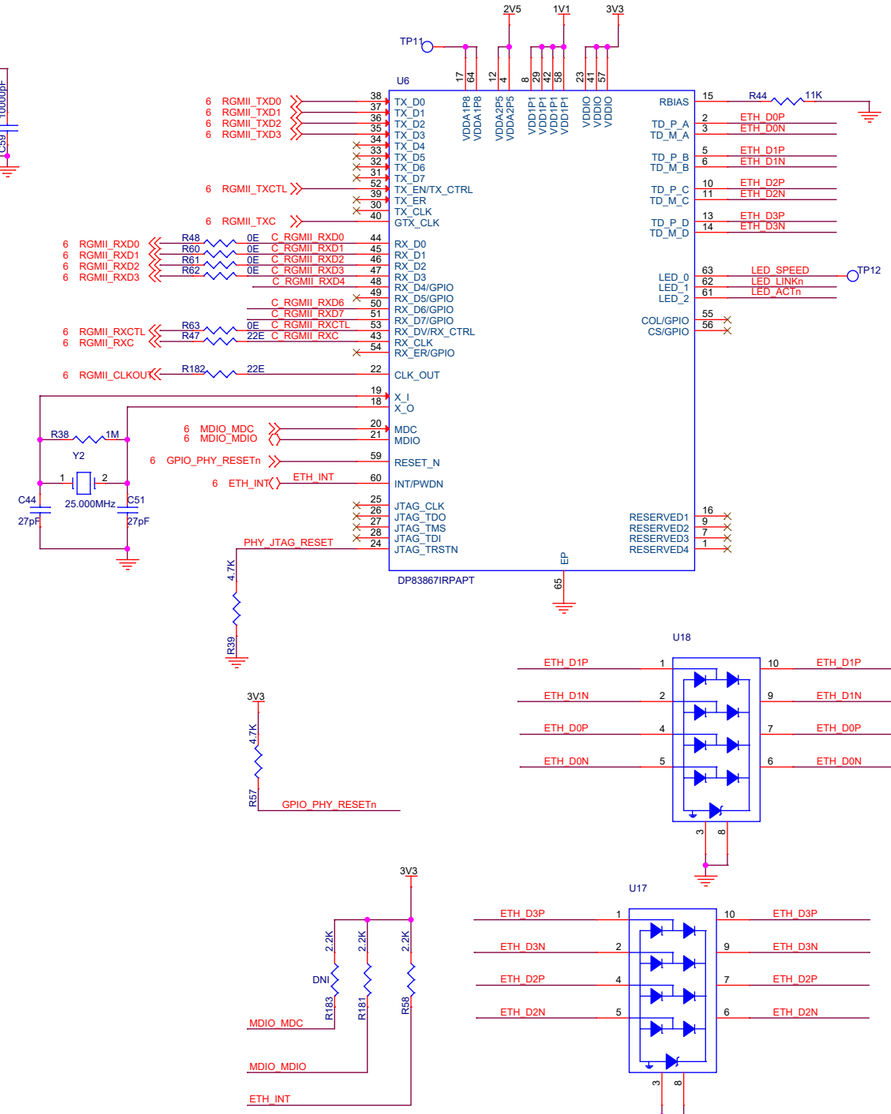
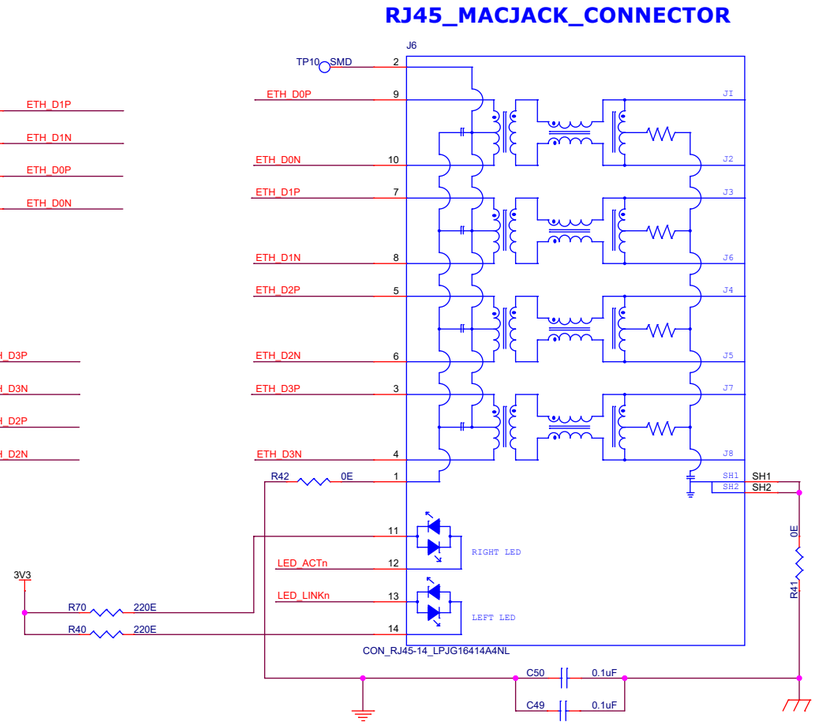
ETHERNET_PHY







RJ45_MACJACK_CONNECTOR



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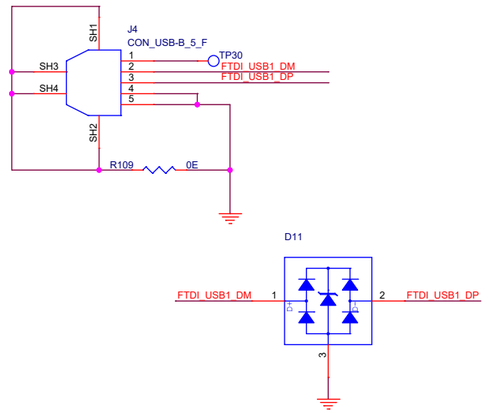
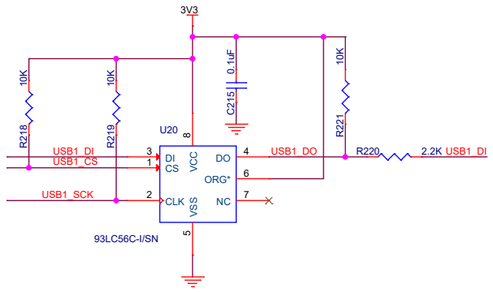
FPGA_FTDI_JTAG

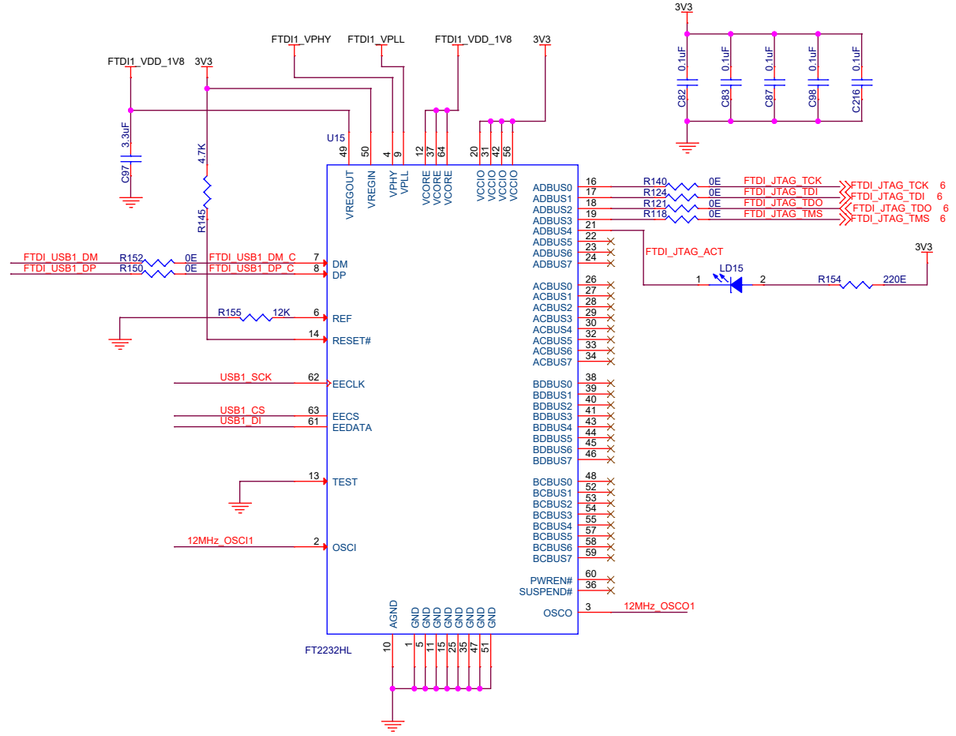
USB_CONN1_FOR_FPGA_PROGRAMMING

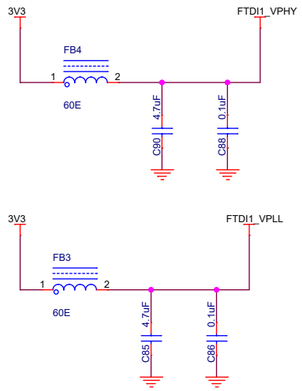


FTDI1_EEPROM

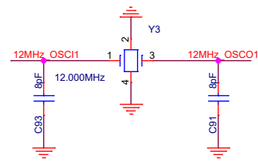


FTDI_CHIP1





FTDI1_12MHz_CRYSTAL



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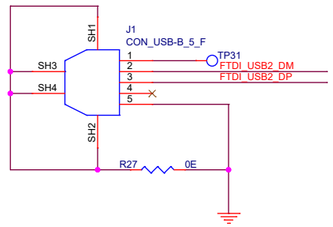
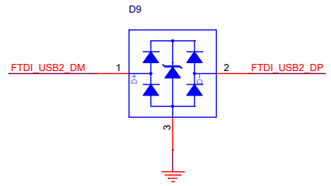
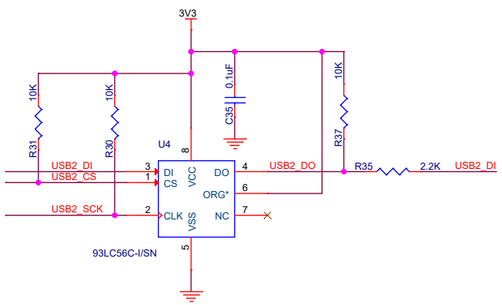
FTDI_UART_SPI_I2C

USB_CONN2_FOR_HOST

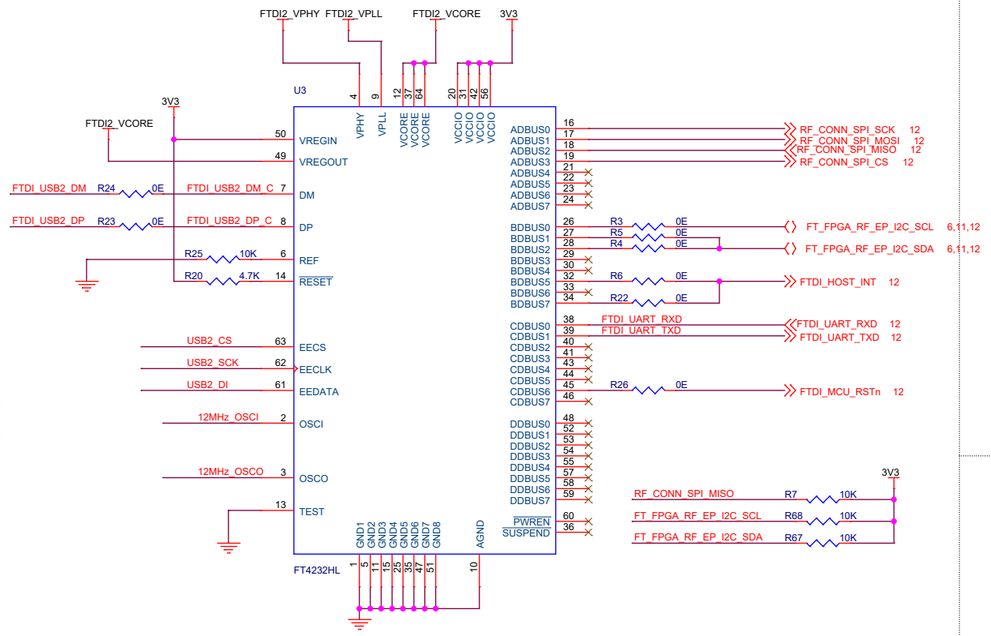


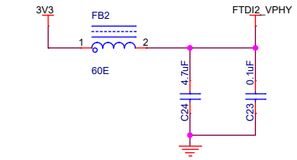


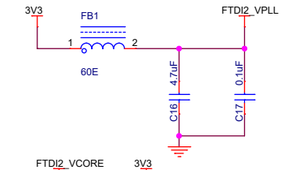
FTDI2_EEPROM

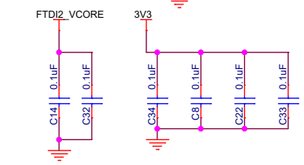


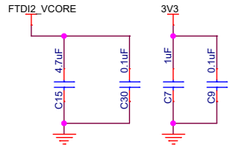
FTDI_CHIP2



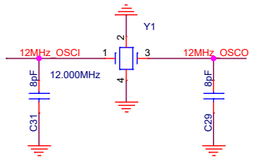








FTDI2_12MHz_CRYSTAL



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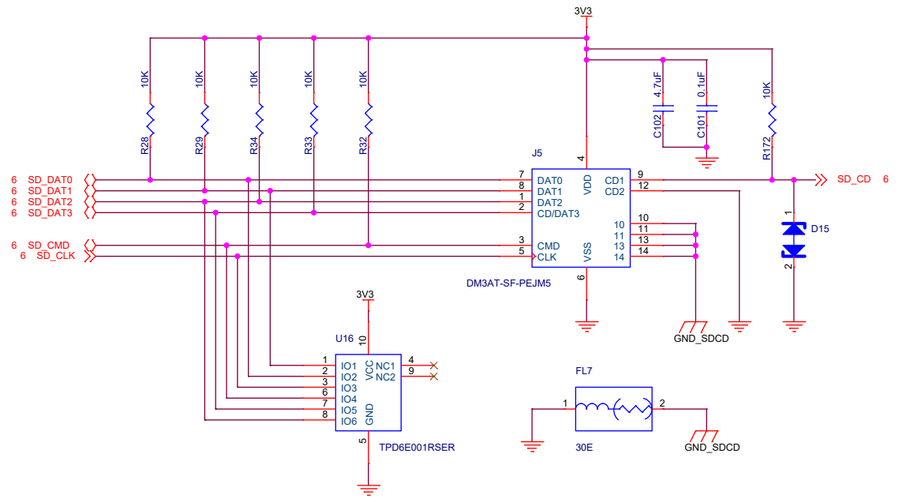
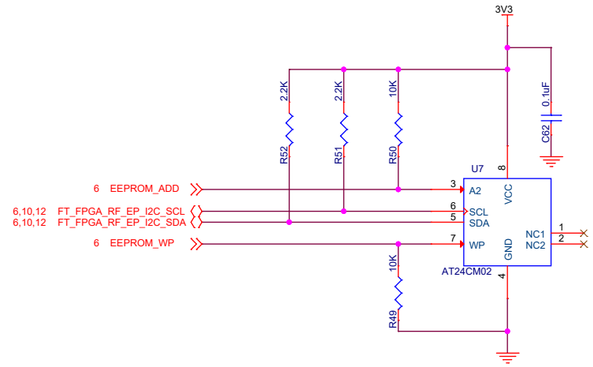
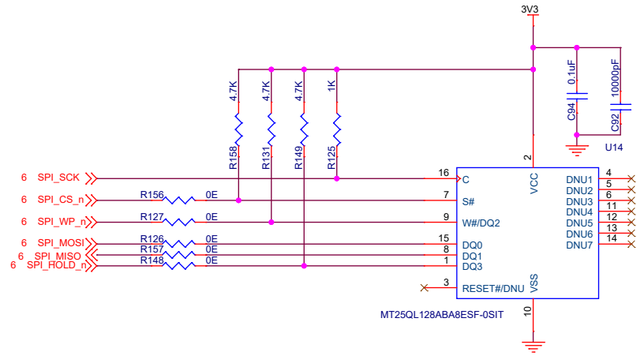
microSD_Card



EEPROM



SPI_FLASH



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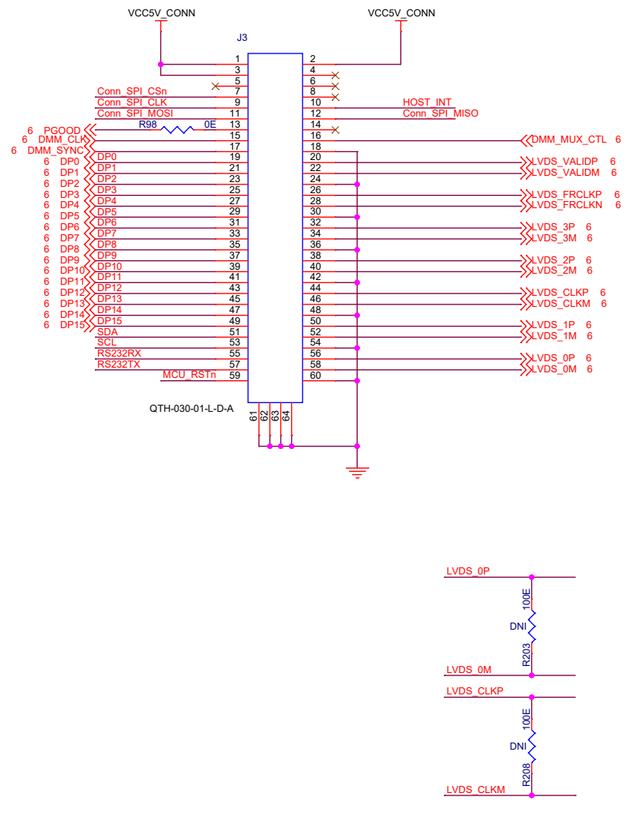
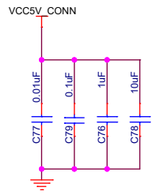
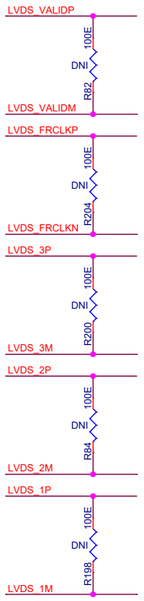
RADAR_EVM_CONNECTOR

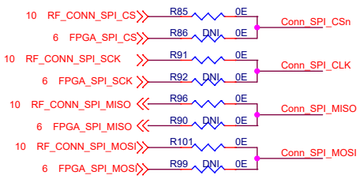
60PIN_CONNECTOR





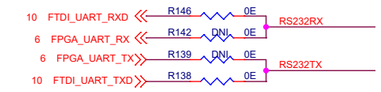


SPI_SELECTION_PATH

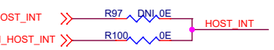


I2C_SELECTION_PATH

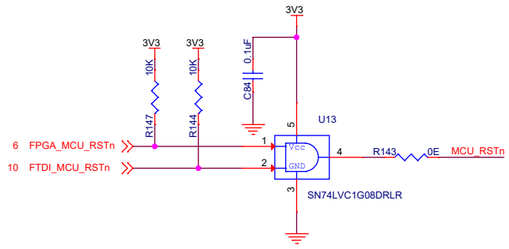
UART_SELECTION_PATH



HOST_INT_SELECTION_PATH



MCU_RSTn_AND_GATE



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HARDWARE

Mounting Holes

MH1
MHOLE_PAN HEAD_M3_NPTH

MH2
MHOLE_PAN HEAD_M3_NPTH

MH3
MHOLE_PAN HEAD_M3_NPTH

MH4
MHOLE_PAN HEAD_M3_NPTH

FIDUCIALS

FID1
FID_40X80

FID2
FID_40X80

FID3
FID_40X80

FID4
FID_40X80

FID5
FID_40X80

FID6
FID_40X80

Samtec 60 pin Cable

ACC1
HQCD-030-02.00-SEU-TBR-1

Ethernet Cable

ACC2
N201-005-GY

uSD CARD

ACC11
SDSDB-008G-B35

Spacers - M3 X 15MM

ACC3
24395

ACC4
24395

ACC5
24395

ACC6
24395

Screws - M3 X 6MM

MH5
PAN HEAD_M3 X 6

MH6
PAN HEAD_M3 X 6

MH7
PAN HEAD_M3 X 6

MH8
PAN HEAD_M3 X 6

MH9
PAN HEAD_M3 X 6

MH10
PAN HEAD_M3 X 6

MH11
PAN HEAD_M3 X 6

MH12
PAN HEAD_M3 X 6

WASHERS - M3 X 0.5MM

ACC7
PLAIN WASHER_M3

ACC8
PLAIN WASHER_M3

ACC9
PLAIN WASHER_M3

ACC10
PLAIN WASHER_M3

LOGOs & LABELs

PCB
LOGO
Texas Intruments

PCB
LOGO
not FCC approved for resale,For Evaluation only;

PCB Number=PRJ_Number
PCB Rev=PCB_Rev
PCB1

PCB
LOGO
WEEE logo

CE
CE Mark

Serial No:
PCB Label
Size: 0.9" x 0.12 "
LBL1

Label Assembly Note
ZZ1
The boards and components must be baked before assembly

Label Assembly Note
ZZ2
Provide serial numbers to the assembled boards for identification

Label Assembly Note
ZZ3
Please carry out the cold points check verification and provide the report for each assembled board

Label Assembly Note
ZZ4
The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

Label Assembly Note
ZZ5
All MSL components should be baked as per JEDEC standard

Label Assembly Note
ZZ6
PCB should be baked at 120 degree for 8 hours

Label Assembly Note
ZZ7
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Label Assembly Note
ZZ8
These assemblies are ESD sensitive, ESD precautions shall be observed.

Label Assembly Note
ZZ9
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Project : DCA1000EVM	Designed for TI by Mistral Solutions Pvt Ltd	Title: HARDWARE
		Size: C; Document Number: PROC048A_SCH; Rev: A
		Date: Tuesday, January 23, 2018; Sheet 13 of 13